



DKZ/138/2011

Warsaw, 11.01.2012

**Re: the open procedure for delivery of the Double Side Mask Alignment System .**

We inform about changes in the Terms of Reference (changed technical parameters are written in a bold font) - Appendix No.1, column "Requirement" in:

- **point 7. Mask and Wafer / Substrate**

The statement of point 7. was written as follows:

*Wafer Size: up to 150 mm*

*Other substrates e.g. ceramic: 6" x 6", substrate thickness: up to 10 mm*

*Pieces: down to <5x5mm*

*Mask Size: SEMI spec, wafer chucks with loading frames for 7"x7" and 5" x 5" masks*

After change point 7. is following:

Wafer Size: up to 150 mm

**Substrate thickness: up to 3mm (standard) and up to 10 mm (if there is no bottom optics)**

**Other substrates e.g. ceramic: 6" x 6", Pieces: down to <5x5mm (chucks have to be included)**

Mask Size: SEMI spec, wafer chucks with loading frames for 7"x7" and 5" x 5" masks

- **point 13. Alignment Stage**

The statement of point 13. was written as follows:

$\geq X: \pm 10mm$

$\geq Y: \pm 5mm$

$\geq \theta: \pm 5^\circ$

*Alignment accuracy  $\geq 0.1 \mu m$*

After change point 13. is following:

$\geq X: \pm 5\text{mm}$

$\geq Y: \pm 5\text{mm}$

$\geq \theta: \pm 3^\circ$

Alignment accuracy  $\geq 0.1 \mu\text{m}$

- **point 15. Bottom side Microscope BSA**

The statement of point 15. was written as follows:

*Split-field*

*Motorized*

*High resolution CCD camera, > 500 lines*

*Range of magnification levels  $\geq 2.5 - 80x$*

*Movement Range Y:  $\geq \pm 10 \text{mm}$*

After change point 15. is following:

Split-field

Motorized

High resolution CCD camera, > 500 lines

**Overall magnification  $\geq 4 - 80x$**

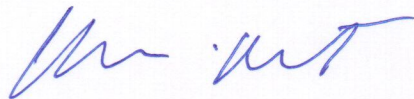
Movement Range Y:  $\geq \pm 10 \text{mm}$

**Note:**

The changes specified above were placed in the Appendix No.1 to the Terms of Reference which is available on the awarding entitie's web site as a Word document.

The present document constitutes as an integral part of the Terms of Reference.

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